

International IOR Rectifier

**RADIATION HARDENED
POWER MOSFET
THRU-HOLE (TO-205AF)**

**IRHF7330SE
JANSR2N7463T2
400V, N-CHANNEL
REF: MIL-PRF-19500/675
RAD Hard™ HEXFET® TECHNOLOGY**

Product Summary

Part Number	Radiation Level	RDS(on)	ID	QPL Part Number
IRHF7330SE	100K Rads (Si)	1.2Ω	3.0A	JANSR2N7463T2



International Rectifier's RADHard™ HEXFET® MOSFET technology provides high performance power MOSFETs for space applications. This technology has over a decade of proven performance and reliability in satellite applications. These devices have been characterized for both Total Dose and Single Event Effects (SEE). The combination of low RDS(on) and low gate charge reduces the power losses in switching applications such as DC to DC converters and motor control. These devices retain all of the well established advantages of MOSFETs such as voltage control, fast switching, ease of paralleling and temperature stability of electrical parameters.

Features:

- Single Event Effect (SEE) Hardened
- Ultra Low RDS(on)
- Low Total Gate Charge
- Proton Tolerant
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Light Weight

Absolute Maximum Ratings

Pre-Irradiation

	Parameter		Units
ID @ VGS = 12V, TC = 25°C	Continuous Drain Current	3.0	A
ID @ VGS = 12V, TC = 100°C	Continuous Drain Current	1.9	
IDM	Pulsed Drain Current ①	12	
PD @ TC = 25°C	Max. Power Dissipation	25	W
	Linear Derating Factor	0.2	W/°C
VGS	Gate-to-Source Voltage	±20	V
EAS	Single Pulse Avalanche Energy ②	140	mJ
IAR	Avalanche Current ①	3.0	A
EAR	Repetitive Avalanche Energy ①	2.5	mJ
dv/dt	Peak Diode Recovery dv/dt ③	6.7	V/ns
TJ	Operating Junction	-55 to 150	°C
TSTG	Storage Temperature Range		
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10 sec.)	
	Weight	0.98 (Typical)	g



Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (Unless Otherwise Specified)

Parameter	Min	Typ	Max	Units	Test Conditions
BV_{DSS}	400	—	—	V	$V_{GS} = 0V, I_D = 1.0mA$
$\Delta BV_{DSS}/\Delta T_J$	—	0.50	—	$V/^\circ\text{C}$	Reference to 25°C , $I_D = 1.0mA$
$R_{DS(on)}$	—	—	1.2	Ω	$V_{GS} = 12V, I_D = 1.9A$ ④
$V_{GS(th)}$	2.5	—	4.5	V	$V_{DS} = V_{GS}, I_D = 1.0mA$
g_{fs}	1.3	—	—	S (τ)	$V_{DS} > 15V, I_{DS} = 1.9A$ ④
I_{DSS}	—	—	50	μA	$V_{DS} = 320V, V_{GS} = 0V$
	—	—	250		$V_{DS} = 320V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	—	—	100	nA	$V_{GS} = 20V$
I_{GSS}	—	—	-100		$V_{GS} = -20V$
Q_g	—	—	41	nC	$V_{GS} = 12V, I_D = 3.0A$ $V_{DS} = 200V$
Q_{gs}	—	—	7.0		
Q_{gd}	—	—	20		
$t_{d(on)}$	—	—	35	ns	$V_{DD} = 200V, I_D = 3.0A,$ $V_{GS} = 12V, R_G = 7.5\Omega$
t_r	—	—	62		
$t_{d(off)}$	—	—	58		
t_f	—	—	58		
$L_S + L_D$	—	7.0	—	nH	Measured from drain lead (6mm/0.25in. from package) to source lead (6mm/0.25in. from package)
C_{iss}	—	555	—	pF	$V_{GS} = 0V, V_{DS} = 25V$ $f = 1.0MHz$
C_{oss}	—	160	—		
C_{rss}	—	60	—		

Source-Drain Diode Ratings and Characteristics

Parameter	Min	Typ	Max	Units	Test Conditions
I_S	—	—	3.0	A	
I_{SM}	—	—	12		
V_{SD}	—	—	1.4	V	$T_j = 25^\circ\text{C}, I_S = 3.0A, V_{GS} = 0V$ ④
t_{rr}	—	—	516	nS	$T_j = 25^\circ\text{C}, I_F = 3.0A, di/dt \leq 100A/\mu\text{s}$ $V_{DD} \leq 50V$ ④
Q_{RR}	—	—	3.0	μC	
t_{on}	Forward Turn-On Time Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$.				

Thermal Resistance

Parameter	Min	Typ	Max	Units	Test Conditions
R_{thJC}	—	—	5.0	$^\circ\text{C/W}$	Typical socket mount
R_{thJA}	—	—	175		

Note: Corresponding Spice and Saber models are available on the G&S Website.

For footnotes refer to the last page

Pre-Irradiation

IRHF7330SE

International Rectifier Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at International Rectifier is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

Table 1. Electrical Characteristics @ Tj = 25°C, Post Total Dose Irradiation ⑤⑥

	Parameter	100K Rads (Si)		Units	Test Conditions ⑧
		Min	Max		
BV _{DSS}	Drain-to-Source Breakdown Voltage	400	—	V	V _{GS} = 0V, I _D = 1.0mA
V _{GS(th)}	Gate Threshold Voltage	2.0	4.5		V _{GS} = V _{DS} , I _D = 1.0mA
I _{GS}	Gate-to-Source Leakage Forward	—	100	nA	V _{GS} = 20V
I _{GSS}	Gate-to-Source Leakage Reverse	—	-100		V _{GS} = -20V
I _{DSS}	Zero Gate Voltage Drain Current	—	50	μA	V _{DS} = 320V, V _{GS} = 0V
R _{DS(on)}	Static Drain-to-Source On-State Resistance ④	—	1.2	Ω	V _{GS} = 12V, I _D = 1.9A
V _{SD}	Diode Forward Voltage ④	—	1.4	V	V _{GS} = 0V, I _D = 3.0A

International Rectifier radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

Table 2. Single Event Effect Safe Operating Area

Ion	LET MeV/(mg/cm ²)	Energy (MeV)	Range (μm)	V _{DS} (V)				
				@V _{GS} = 0V	@V _{GS} = -5V	@V _{GS} = -10V	@V _{GS} = -15V	@V _{GS} = -20V
Cu	28	285	43	325	325	325	325	—
Br	36.8	305	39	325	325	325	275	—

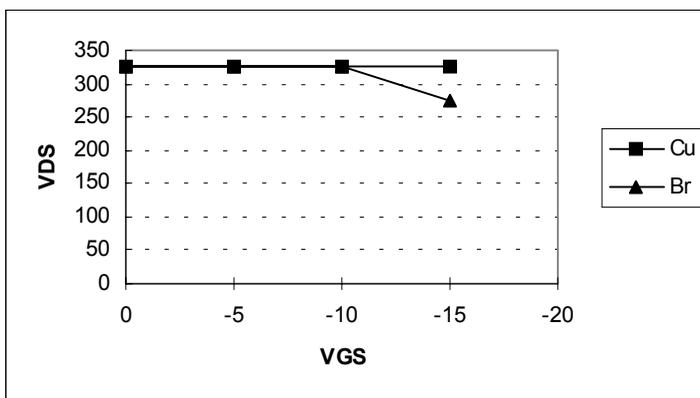


Fig a. Single Event Effect, Safe Operating Area

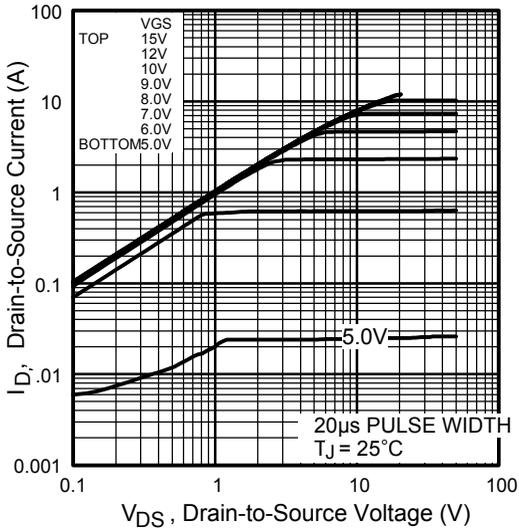


Fig 1. Typical Output Characteristics

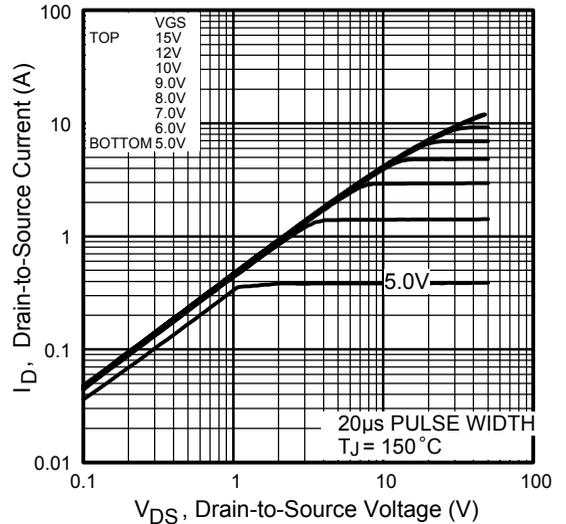


Fig 2. Typical Output Characteristics

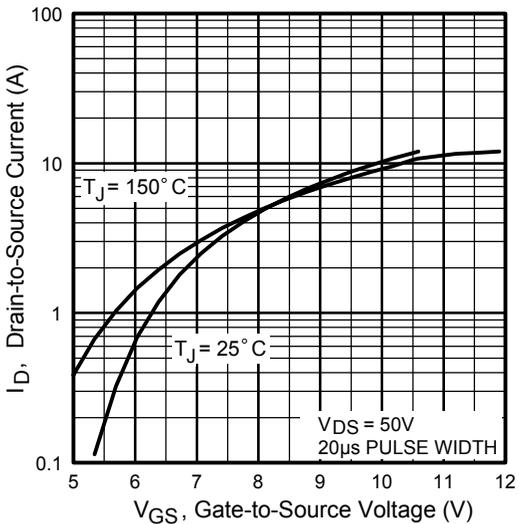


Fig 3. Typical Transfer Characteristics

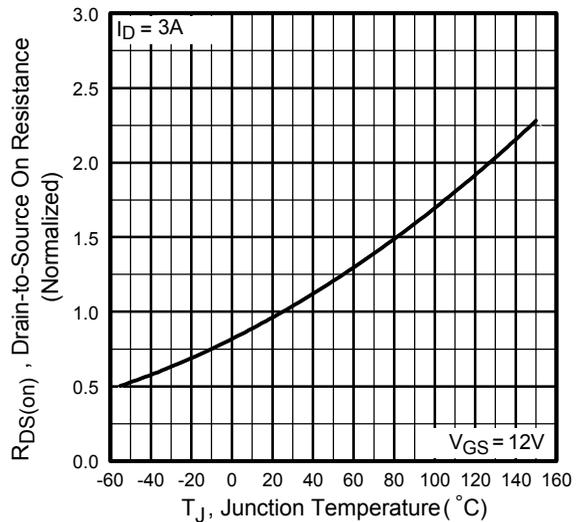


Fig 4. Normalized On-Resistance
Vs. Temperature

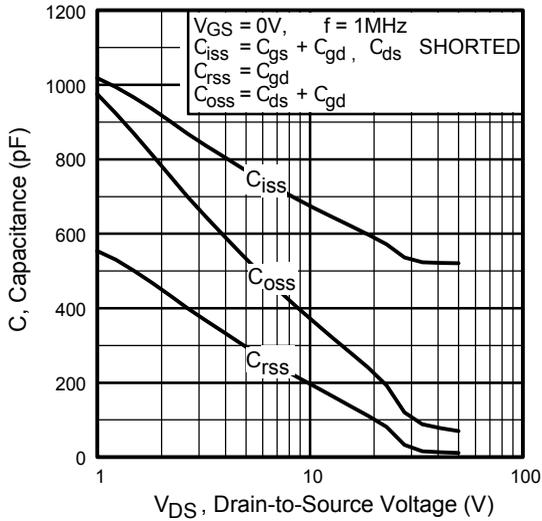


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

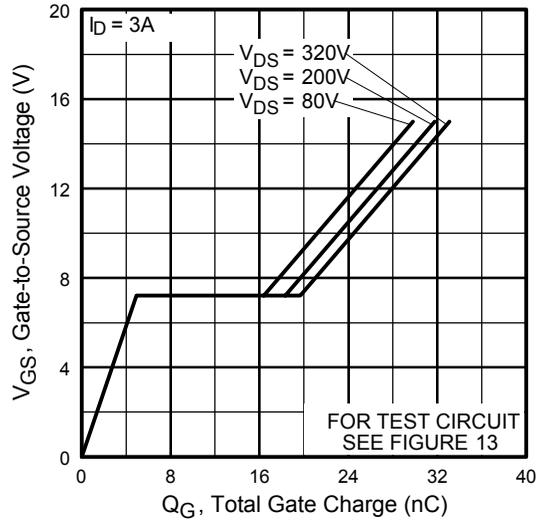


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

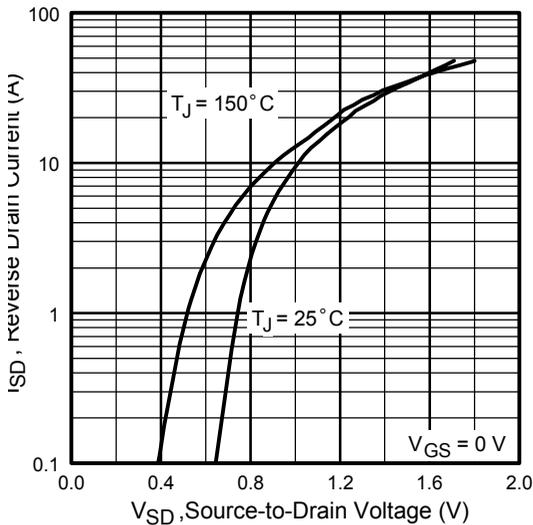


Fig 7. Typical Source-Drain Diode Forward Voltage

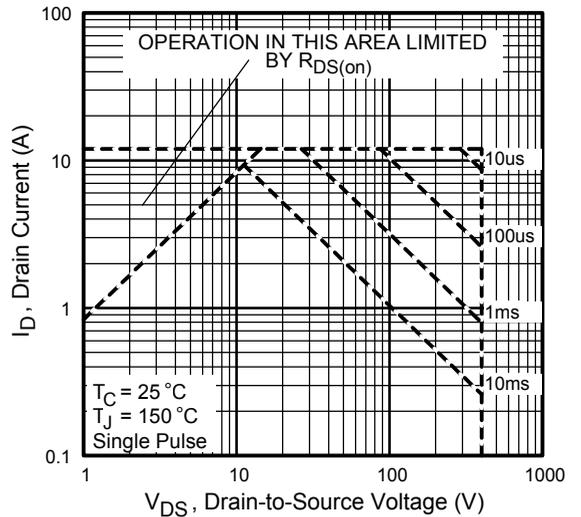


Fig 8. Maximum Safe Operating Area

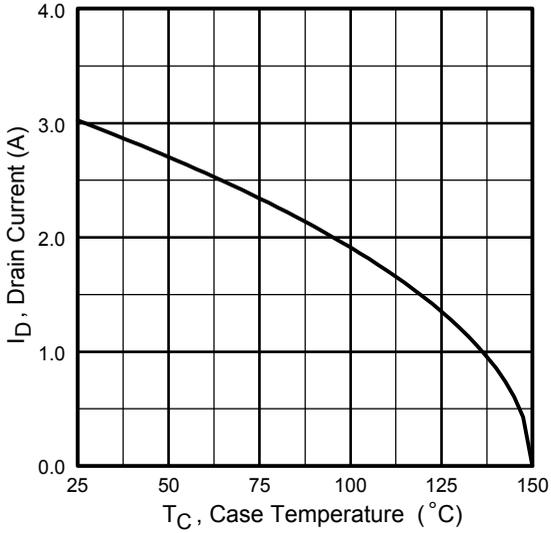


Fig 9. Maximum Drain Current Vs. Case Temperature

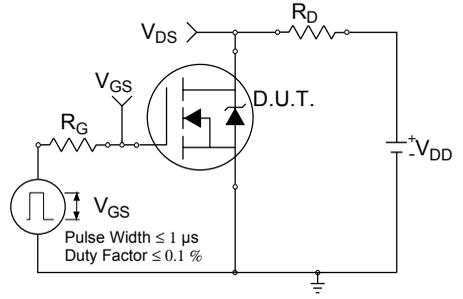


Fig 10a. Switching Time Test Circuit

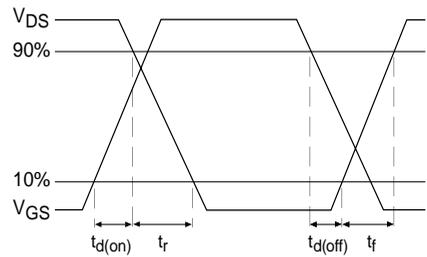


Fig 10b. Switching Time Waveforms

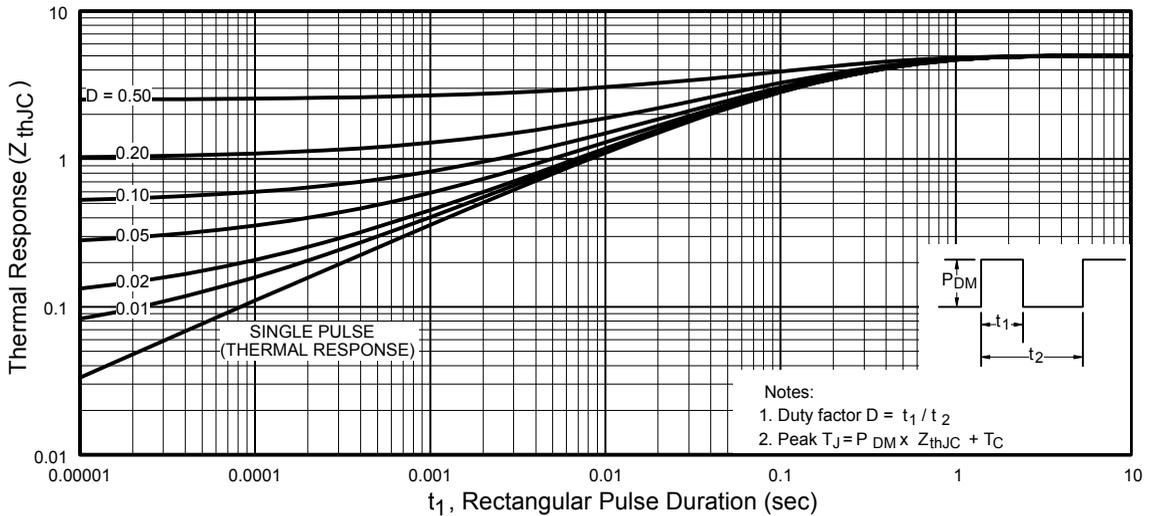


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

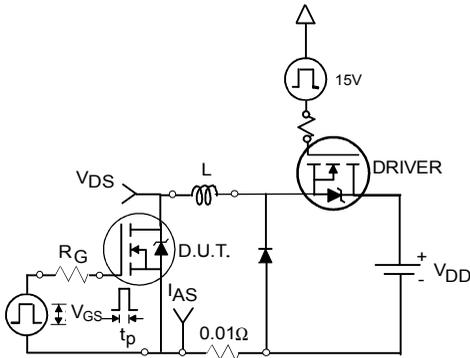


Fig 12a. Unclamped Inductive Test Circuit

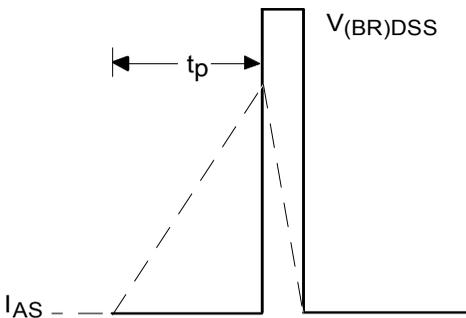


Fig 12b. Unclamped Inductive Waveforms

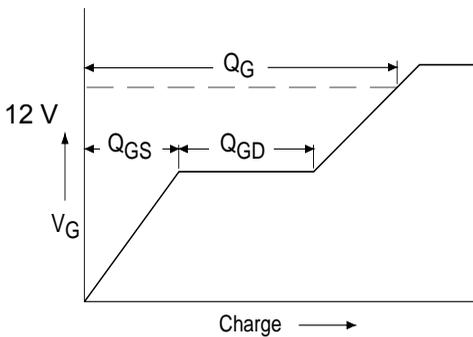


Fig 13a. Basic Gate Charge Waveform

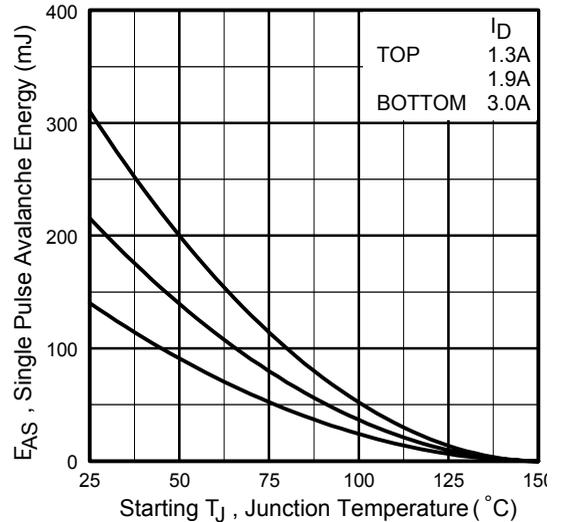


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

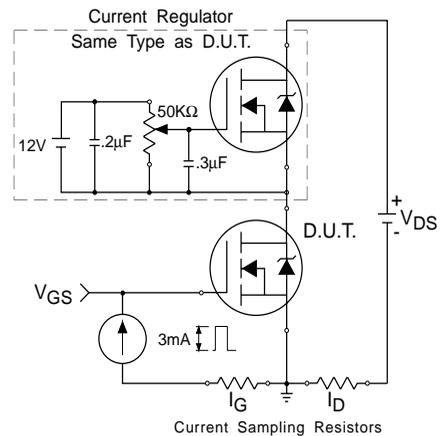
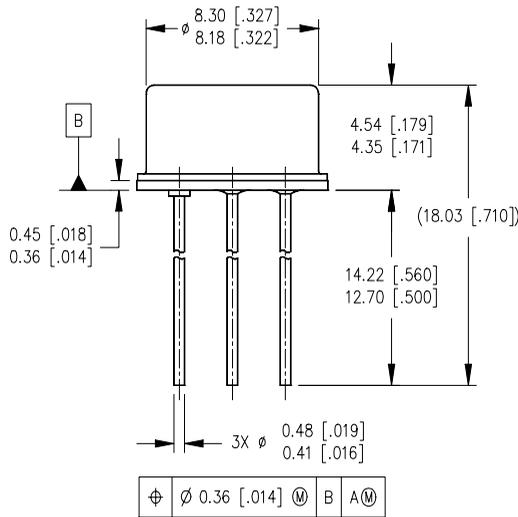


Fig 13b. Gate Charge Test Circuit

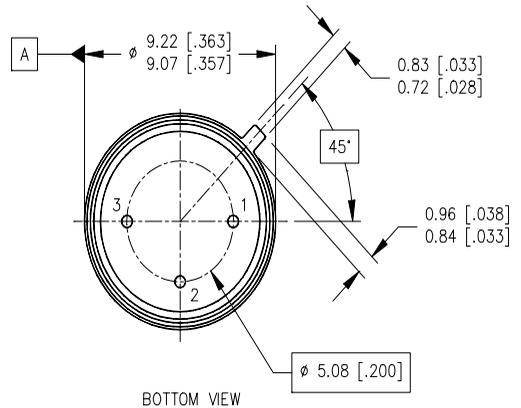
Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ② $V_{DD} = 50V$, starting $T_J = 25^\circ C$, $L = 31\text{ mH}$
Peak $I_L = 3.0A$, $V_{GS} = 12V$
- ③ $I_{SD} \leq 3.0A$, $di/dt \leq 400A/\mu s$,
 $V_{DD} \leq 400V$, $T_J \leq 150^\circ C$
- ④ Pulse width $\leq 300\ \mu s$; Duty Cycle $\leq 2\%$
- ⑤ **Total Dose Irradiation with V_{GS} Bias.**
12 volt V_{GS} applied and $V_{DS} = 0$ during irradiation per MIL-STD-750, method 1019, condition A.
- ⑥ **Total Dose Irradiation with V_{DS} Bias.**
320 volt V_{DS} applied and $V_{GS} = 0$ during irradiation per MIL-STD-750, method 1019, condition A.

Case Outline and Dimensions —TO-205AF (Modified TO-39)



SIDE VIEW



BOTTOM VIEW

LEGEND

- 1- SOURCE
- 2- GATE
- 3- DRAIN

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME 14.5M-1994.
- 2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- 3. CONTROLLING DIMENSION: INCH.
- 4. CONFORMS TO JEDEC OUTLINE TO-205AF (TO-39).